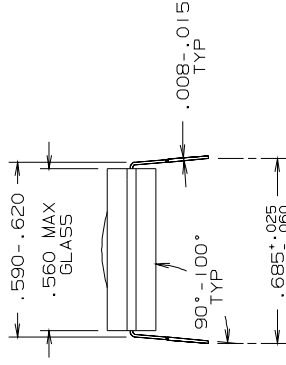
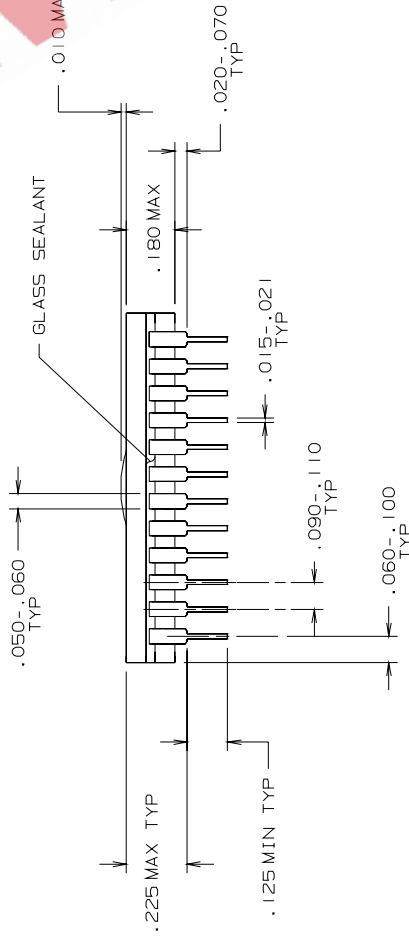
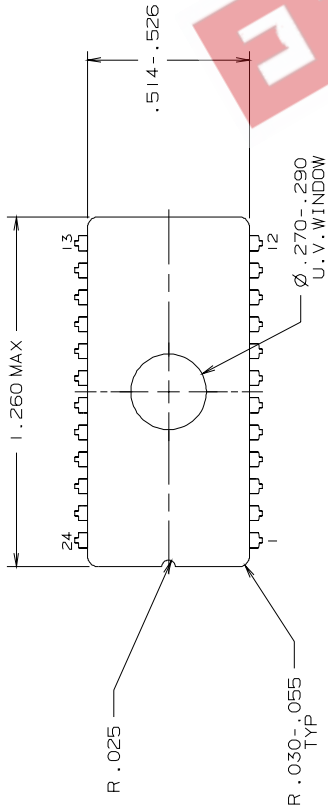


R E V I S I O N S			
LTR	DESCRIPTION	E.C.N.	DATE
G	REVISE AND REDRAW	09001	01/08/92
			BY/APP'D DEG



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MILABRO
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 200-800 MICROINCHES TIN PLATE OVER 50-300 MICROINCHES NICKEL UNDERPLATE OR BASIS METAL.
 - 50-100 MICROINCHES GOLD OVER 50-350 MICROINCHES NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
- NO JEDEC REGISTRATION AS OF 12/16/91.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION	
DRAWN D.E. GRADY	01/08/92	2500 Semiconductor Drive, Santa Clara, CA 95052-8090	
DT'G. CHK.		CERDIP (JQ),	
ENGR. CHK.		24 LEAD EPROM,	
APPROVAL		SMALL WINDOW	
PROJECTION		SCALE	DRAWING NUMBER
1:1		N/A	C MKT-J24AQ
		REV	G
		FORMERLY:	N/A SHEET 1 OF 1